



Photonics Integration on Silicon-on-Insulator and Thin-Film Lithium Niobate Platforms

Guest Editor:

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Deadline for manuscript
submissions:

30 June 2024

Message from the Guest Editor

Dear Colleagues,

We are delighted to invite you to submit your original or review papers to our upcoming Special Issue on heterogeneous integrated photonics on SOI and TFLN platforms. This Special Issue will be published in Photonics. This special issue aims to present the latest research and development activities on heterogeneous integration technologies on the SOI and TFLN platforms, covering passive components and various active devices. The special issue invites original and review articles on the design and fabrication of heterogeneous integration of SOI and TFLN photonic devices, exploring their tremendous potential in communication, computation, quantum information, and other fields. All submitted papers will be peer-reviewed and evaluated based on their originality, significance, and contribution to the field. The accepted papers will be published in Photonics as part of the Special Issue.

Thank you for considering our invitation to contribute to Photonics. We eagerly anticipate receiving your submissions.

Guest Editors,

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mdpi.com/si/172156

Special Issue